### DATA SHEET

### **DEVICE NUMBER: BWL-10C3B06**

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2010.01.09	1.0	1.0	1.0	1.0	1.0	1.0			Preliminary
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### 佰鴻工業股份有限公司

BRIGHT LED ELECTRONICS CORP.

台北縣板橋市和平路19號3樓

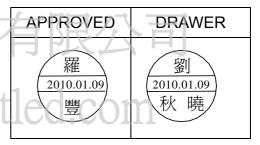
3F., No. 19, Ho Ping Road, Pan Chiao City,

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Tel: 886-2-29591090

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BWL-10C3B06

#### Features:

1. Input power: 3W.

2. Chip material: InGaN.

3. Emitted color: Blue.

4. High lumen output.

5. High flux density.

6. Low power consumption.

7. Efficient heat transfer.

8. Exterior lens is PC.

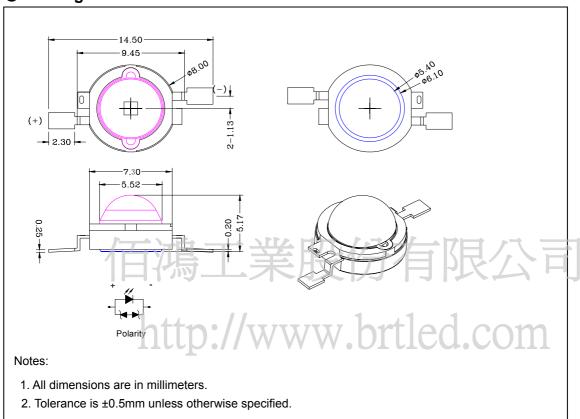
9. Add extra heat sink is necessary.

\* Must increasing heatsink, let the unit temperature below 60  $^{\circ}$ C.

### Applications:

- 1. Torch.
- 2. Head Light.
- 3. Architectural Lighting.
- 4. LCD Backlight.

### Package dimensions :







BWL-10C3B06

### ■ Absolute maximum ratings (T<sub>J</sub>=25°C)

Parameter	Symbol	Rating	Unit	
Power Dissipation	$P_D$	3.0	W	
DC Forward Current*1	I <sub>F</sub>	700	mA	
Peak Pulsed Forward Current*2	I <sub>FP</sub>	2.0	А	
LED Junction Temperature	TJ	130	°C	
Operating Temperature	Topr	-30~120	°C	
Storage Temperature	Tstg	-40~120	°C	
Reverse Voltage	V <sub>R</sub>	5	V	
Soldering Temperature (T=5 sec)	Tsol	300 ± 5	°C	

<sup>\*1</sup>Proper current derating must be followed to keep LED junction temperature (T<sub>J</sub>) below the maximum.

### ● Electrical & Optical Characteristics (T<sub>J</sub>=25°C)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =700mA	-	3.9	4.5	V
Total Flux	Ф	I <sub>F</sub> =700mA	24	25	-	lm
Peak Wavelength	λр	I <sub>F</sub> =700mA	-	460	-	nm
Dominant Wavelength	λd	I <sub>F</sub> =700mA	460	-	470	nm
Spectral Line Half-width	<u> </u>	I <sub>F</sub> =700mA	臣方	25	-	nm
Reverse Current	R	V <sub>R</sub> =5V		I,	10	μA
Thermal Resistance, Junction To Case	$R heta_{J-C}$	I <sub>F</sub> =700mA	<u>.</u>	9	-	°C/W
Viewing Angle	2θ <sub>1/2</sub>	I <sub>F</sub> =700mA	. <u></u> U	120	-	degree

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 $<sup>^{*2}</sup>$ Condition for I<sub>FP</sub> is pulsed with 1/10 duty and 0.1msec width.



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### Typical electro-optical characteristics curves

Fig.1 RELATIVE INTENSITY VS. WAVELENGTH

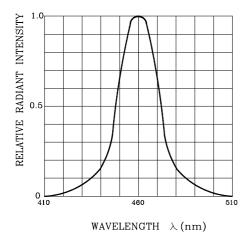


Fig.3 FORWARD CURRENT VS. FORWARD VOLTAGE

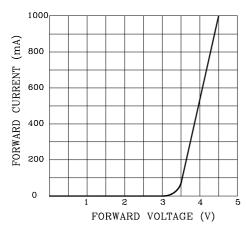


Fig.5 RELATIVE LUMINOUS INTENSITY

VS. FORWARD CURRENT

0.4

RELATIVE LUMINOUS INTENSITY(@700mA) 2.0 1.5 1.0 0.5

0.6

FORWARD CURRENT (A)

0.8

1.0

Fig.2 FORWARD CURRENT DERATNG CURVE

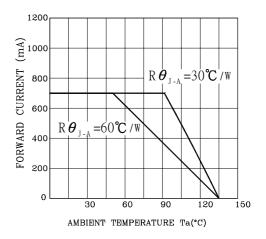
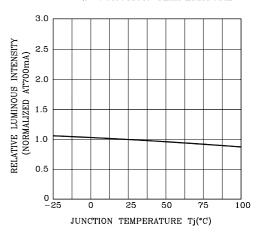
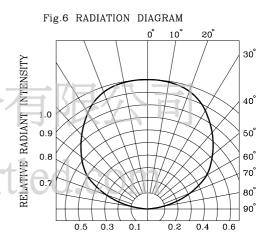


Fig.4 RELATIVE LUMINOUS INTENSITY VS. JUNCTION TEMPERATURE

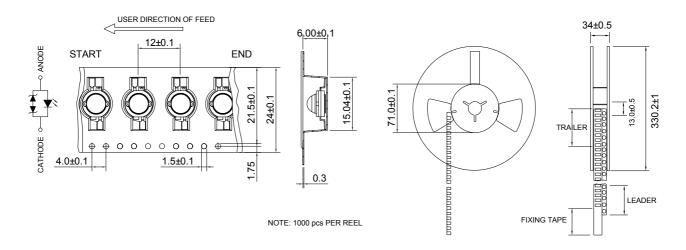




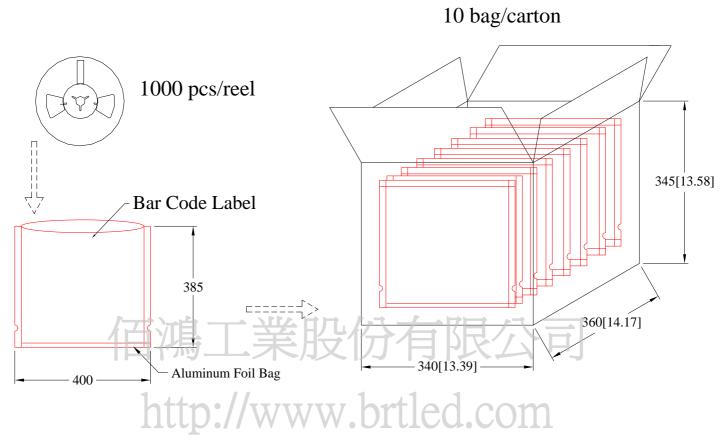


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#### Tapping and packaging specifications(Units: mm)



#### Package Method : (unit:mm)



NOTES : Bag : Tolerance is  $\pm$  5 mm unless otherwise noted. Carton : Tolerance is  $\pm$  10 mm unless otherwise noted.



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### Total Flux Bin Limits (At 700mA)

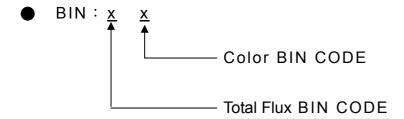
BIN CODE	Min. (lm)	Max. (lm)
J	24	25
К	25	33

Tolerance for each Bin limit is ± 15 %

### Color Bin Limits(At 700mA)

BIN CODE	Min. (nm)	Max. (nm)
3	460	465
4	465	470

Tolerance for each Bin limit is ± 1 nm



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#### Notes:

1. Bin categories are established for classification of products. Products may not be available in all bin categories.



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#### Notes for designing:

Current limiting resistor or a constant current power supply must be used in the circuit to drive BRIGHT LEDs within the rated figures and not to overload BRIGHT LEDs with instantaneous voltage at the turning ON and OFF cycles.

When using pulse driving, the average current must be within the rated figures. And the circuit should be designed to avoid reverse voltage when turning off the BRIGHT LEDs.

#### Storage:

In order to avoid the absorption of moisture, it is recommended to solder BRIGHT LEDs as soon as possible after unpacking the sealed envelope.

If the envelope is still packed, to store it in the environment as following:

- (1) Temperature : 5°C-30°C (41°F)Humidity : RH 60% Max.
- (2) After this bag is opened:
- a. Completed within 168 hours.
- b. Stored at less than 30% RH.
- (3) Devices require baking before mounting, if:
  - (2) a or (2) b is not met.
- (4) If baking is required, devices must be baked under below conditions: 48 hours at 60°C±3°C.
- Package and Label of Products:
- (1) Package: Products are packed in one bag of 1000 pcs (one taping reel) and a label is attached to each bag.
- (2) Label:

